

RoHS MATERIAL DECLARATION, POWER RESISTOR MHP

COMPONENTS	MATERIAL	CAS No.	SMHP20
Substrate	2-Aluminum 3-Oxide	1344-28-1	69.651
	Silicone 2-Oxide	14808-60-7	1.897
	Calcium Oxide	1305-78-8	1.106
	Magnesium Oxide	1309-48-4	0.586
Conductor	Copper	7440-50-8	0.092
Resistor	Nickel, 70%	7440-02-0	0.016
	Chromium, 30%	7440-47-3	0.008
Passivation	Epoxy	25036-25-3	0.497
Solder, high temp	Lead	7439-92-1	9.000
	Tin	7440-31-5	1.000
Solder, low temp	Tin	7440-31-5	9.650
	Silver	7440-22-4	0.300
	Copper	7440-50-8	0.050
Terminal	Copper	7440-50-8	66.250
	Tin, plating	7440-31-5	2.250
Mold, red	Epoxy	25036-25-3	
Mold, black	Silica, fusion	60676-86-0	302.155
	Epoxy	29690-82-2	129.495
Flange	Copper	7440-50-8	928.400
	Nickel, plating	7440-02-0	7.600
TOTAL	Weight (milligrams)		1,530.003